

New gold electrolyte with autocatalytic properties and non-toxic stabilization

0.6

g/l gold content in plating solution

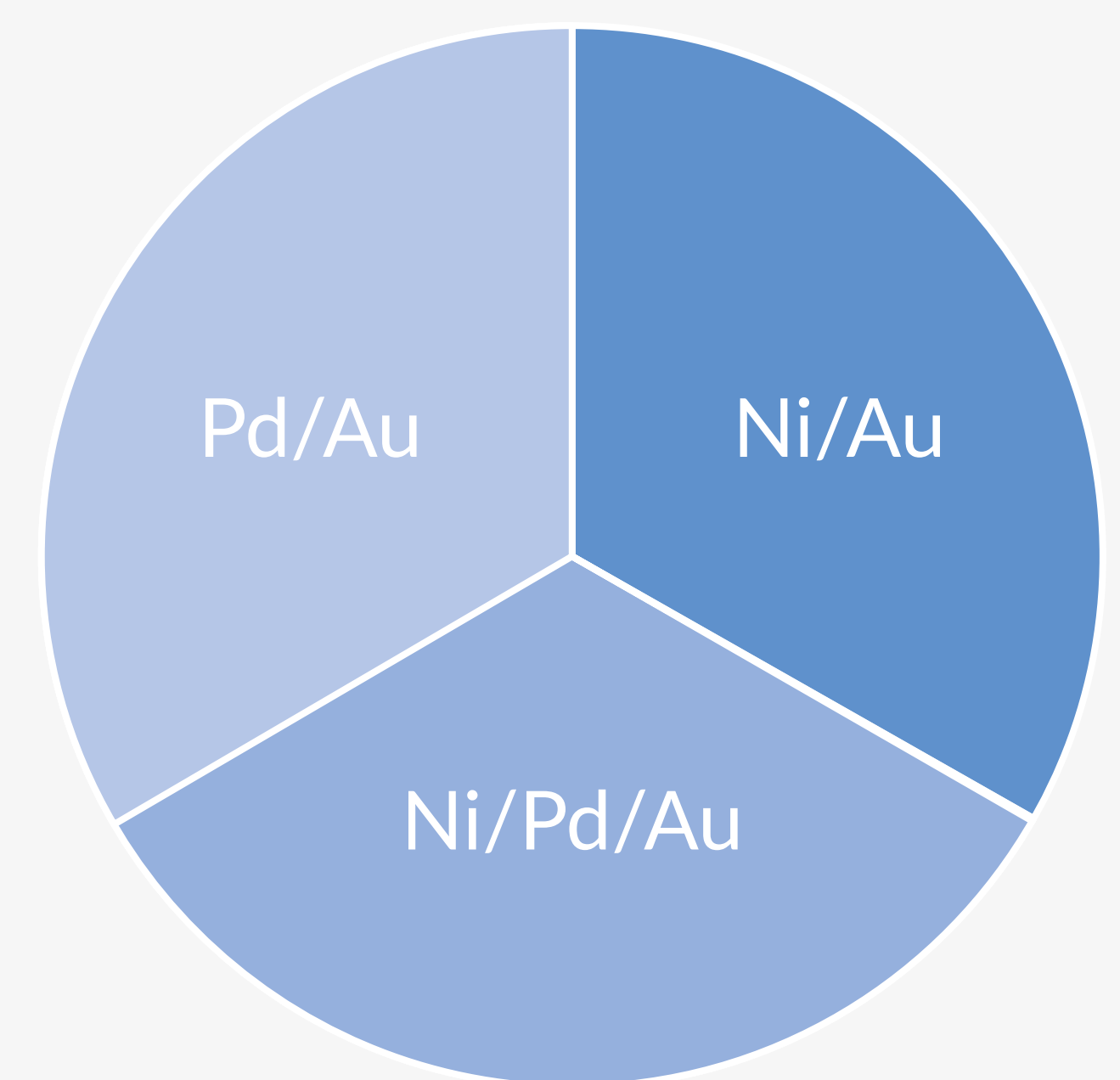
5%

COV thickness distribution and lower

Non-toxic stabilizer



Versatile electrolyte



Latest generation corrosion-free gold for ENIG, ENEPIG, and EPAG

Aurotech® G-Bond 3 is the latest generation gold electrolyte that fulfills all industry standards for ENIG, ENEPIG, and EPAG plating. It exhibits autocatalytic plating properties to mitigate the attack to the underlying layer and enables the plating of high gold thickness where required. Besides offering the highest bath stability and excellent layer performance, the process exhibits the benefit of non-toxic stabilization so that no handling of KCN replenishment is required. The new process combines the known benefits of Aurotech® G-Bond 2 with outstanding stability, long bath life, and a new and toxic-free stabilizer.

Features and benefits

- Non-toxic stabilizer, no KCN handling required for replenishment
- Low Au-content (0.6 g/l)
- High bath stability, no plate out
- ENIG corrosion level 0 and 1
- Excellent thickness distribution of < 5% COV